







PRODUCT NUMBER 10019364-002 TYCO PLUG KIT WITH UNCOUALIZED PCB 10019364-002 TYCO PLUG KIT WITHOUT PCB 10019364-003 TYCO PLUG KIT WITH COUALIZED PCB WITHOUT COMPONENTS 10019364-004 TYCO PLUG KIT WITH COUALIZED PCB WITHOUT COMPONENTS 10019364-004 TYCO PLUG KIT WITH COUALIZED PCB WITH COMPONENTS • ADD LF TO END OF PART NUMBER FOR LEAD FREE SOLDER TAILS EXAMPLE: 10019364-001LF, SEE LEAD FREE SOLDER TAILS EXAMPLE: 10019364-001LF, SEE LEAD FREE SOLDER TAILS EXAMPLE: 10019364-001LF, SEE LEAD FREE SOLDER TAILS ** APPLICATION SPECIFICATION GS-12-209 4. MATERIAL: ** CONTACT AREA AND TIN/LEAD PLATING ON SOLDER TAIL UNLESS PART NUMBER ERDS LF, LEAD FREE SOLDER TAIL UNLESS PART NUMBER ERDS LF, LEAD FREE SOLDER TAIL UNLESS PART NUMBER ERDS LF, LEAD FREE SOLDER TAIL UNLESS ** PART NUMBER ERDS LF, LEAD FREE SOLDER TAIL UNLESS ** PART NUMBER ERDS LF, LEAD FREE SOLDER TAIL UNLESS ** PART NUMBER ERDS LF, LEAD FREE SOLDER TAIL UNLESS ** SHELLS: ZINC WITH NICKEL PLATING ON SOLDER TAIL UNLESS ** SHELLS: ZINC WITH NICKEL PLATING AND COPPER UNDERPLATING ** PULL TAB & CABLE COLLAR: THERMOPLASTIC ** LEAD FREE PART NUMBER, THE HOUSING WILL WITHSTAND EXPERIENCE ** STATE STAINLESS STEEL* ** STATE WITH RECEPTACLE 58366 OR 58367.** ** LEAD FREE PART NUMBER, THE HOUSING WILL WITHSTAND EXPENDENT OF PCB LOCATED FROM DATUM A & B. ** APPLICATION WITH A 1. GEMMEN MITH THE CREDITED BOARD.** ** OF PCB LOCATED FROM DATUM A & B. ** APPLICATION WITH A 1. GEMMEN MITH THE CREDITED BOARD.** ** APPLICATION WITH A 1. GEMMEN MITH THE CREDITED BOARD.** ** APPLICATION WITH A 1. GEMMEN MITH THE CREDITED BOARD.** ** APPLICATION WITH A 1. GEMMEN MITH THE CREDITED BOARD.** ** APPLICATION WITH A 1. GEMMEN MITH THE CREDITED BOARD.** ** APPLICATION WITH A 1. GEMMEN MITH THE CREDITED BOARD.** ** APPLICATION WITH A 1. GEMMEN MITH THE CREDITED BOARD.** ** APPLICATION WITH A 1. GEMMEN MITH THE CREDITED BOARD.** ** APPLICATION WITH A 1. GEMMEN MITH THE CREDITED BOARD.** ** APPLICATION WITH A 1. GEMMEN MITH THE CREDITED BOARD.** ** APPLICATION WITH A 1.	1	2	3	4
10019364-002 TYCO PLUG KIT WITH EQUALIZED PCB WITHOUT COMPONENTS	L L C C D L D	TION		
TYCO PLUG KIT WITH EQUALIZED PCB WITHOUT COMPONENTS		D PCB		
1		DOB WITHOUT COMPONENTS		
* ADD LF TO END OF PART NUMBER FOR LEAD FREE SOLDER TAILS EXAMPLE: 10019364-001LF, SEE LEAD FREE NOTES BELOW. NOTES: 1. PACKAGING SPECIFICATION GS-14-794 2. APPLICATION SPECIFICATION GS-20-026 FOR PADDLE CARD AND CABLE TERMINATION DETAILS. 3. PRODUCT SPECIFICATION GS-12-209 4. MATERIAL: CONTACT AREA AND TIN/LEAD PLATING ON SOLDER TAIL UNLESS PART NUMBER RIDS LF, LEAD FREE SOLDER TAIL PLATING 2um (80v") MIN MATTE TIN OVER 1.77um (S0v") MIN NICKEL UNDERPLATE. HOUSING: HIGH TEMPERATURE THERMOPLASTIC, UL 94V-0 RATED, SUITABLE FOR REFLOW SOLDERING. SHELLS: ZINC WITH NICKEL PLATING AND COPPER UNDERPLATING PULL TAB & CABLE COLLAR: THERMOPLASTIC LATCH: STAINLESS STEEL 5. MATES WITH RECEPTACLE 58366 OR 58367. PCB NOTES: 1. PADS ON BOTH SIDESOF PCB. 2. DIMENSIONS APPLY TO BOTH SIDES OF PCB LOCATED FROM DATUM A & B. 3. THIS AREA NOT TO BE USED TO LOCATE SOLDER TAILS TO SOLDER PADS. THIS AREA IS TO AID IN ASSEMBLY BY LIMITING THE TOP & BOITOM MOVEMENT OF THE PADDLE CARD. 3. LEAD FREE PRODUCTS MEET EUROPEAN UNION DIRECTIVES AND OTH ASSEMBLY BY LIMITING THE TOP & BOITOM MOVEMENT OF THE PADDLE CARD.				
1. PACKAGING SPECIFICATION: GS-14-794 2. APPLICATION SPECIFICATION GS-20-026 FOR PADDLE CARD AND CABLE TERMINATION DETAILS. 3. PRODUCT SPECIFICATION GS-12-209 4. MATERIAL: CONTACTS: COPPER ALLOY WITH GOLD OVER NICKEL PLATING IN THE CONTACTS: COPPER ALLOY WITH GOLD OVER NICKEL PLATING IN THE CONTACTS: COPPER ALLOY WITH GOLD OVER NICKEL PLATING ON SOLDER TAIL UNLESS PART NUMBER ENDS LF, LEAD FREE SOLDER TAIL PLATING 2 um (80 u") MIN MATTE TIN OVER 1.27 um (50 u") MIN NICKEL PLATING 2 um (80 u") WIN MATES WITH REMEMBERATURE THERMOPLASTIC, UL 94V-0 RATED, SUITABLE FOR REFLOW SOLDERING. SHELLS: ZINC WITH NICKEL PLATING AND COPPER UNDERPLATING PULL TAB & CABLE COLLAR: THERMOPLASTIC LATCH: STAINLESS STEEL 5. MATES WITH RECEPTACLE 58366 OR 58367. LEAD FREE NOTES: 1. IF LEAD FREE PART NUMBER, THE HOUSING WILL WITHSTAND EXPENSED TO 260°C PEAK TEMPERATURE FOR 10 SECONDS IN A WAVE SOLDER APPLICATION WITH A 1.60mm MIN THICK CIRCUIT BOARD. 2. DIMENSIONS APPLY TO BOTH SIDES OF PCB. 2. DIMENSIONS APPLY TO BOTH SIDES OF PCB LOCATE SOLDER APPLICATION WITH A 1.60mm MIN THICK CIRCUIT BOARD. 3. LEAD FREE PRODUCTS MEET EUROPEAN UNION DIRECTIVES AND OTH COUNTRY REGULATIONS AS DESCRIBED IN GS-22-008.	ADD LF TO END OF PART NUMBER FOR LEAD FREE	SOLDER TAILS		
CABLE TERMINATION DETAILS. 3. PRODUCT SPECIFICATION GS-12-209 4. MATERIAL:		94		
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4. PCB THICKNESS: 1.57mm (.062).	TAILS TO SOLDER PADS. THIS AREA ASSEMBLY BY LIMITING THE TOP &	A IS TO AID IN COUNTR		
	4. PCB THICKNESS: 1.57mm (.062).			

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For TYCO

³PDM: Rev:F

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